



Initial Product/Process Change Notification

Document #: IPCN23660Z

Issue Date: 28 Sep 2023

Title of Change:	Additional wafer fabrication facility for ONBCD25 technology in onsemi Aizu located in Aizu, Japan.	
Proposed Changed Material First Ship Date:	19 Jun 2024 or earlier if approved by customer	
Current Material Last Order Date:	N/A <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>	
Current Material Last Delivery Date:	N/A <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>	
Product Category:	Active components – Integrated circuits	
Contact information:	Contact your local onsemi Sales Office or PCNSupport@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office or Jacob.Saliba@onsemi.com	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 6 months prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >.	
Change Category		
Category	Type of Change	
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor	
Description and Purpose:		
	From	To
Fab Site	onsemi Gresham, US	onsemi Gresham, US or onsemi Aizu, Japan
There is no product marking change as a result of this change		
Reason / Motivation for Change:	Capacity improvement	
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device will be qualified and validated based on the same Product Specification. No anticipated impacts.	



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Sites Affected:			
onsemi Sites		External Foundry/Subcon Sites	
onsemi Aizu, Japan		None	
Marking of Parts/ Traceability of Change:		No change to marking / Changed material may be identified by date code	
Reliability Data Summary:			
QV DEVICE NAME: NCV6324BMTAAWTBG			
RMS: S90590			
PACKAGE: WDFN8 AU SNGL HPBF WFS			
Test	Specification	Condition	Interval
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Early Life Failure Rate	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	1000 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Electrical Characteristics Summary:			
Electrical characteristics are not impacted.			

List of Affected Parts:		
Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u> .		
Current Part Number	New Part Number	Qualification Vehicle
NCV6323BMTAATBG	N/A	NCV6324BMTAAWTBG
NCV6323BMTAAWTBG	N/A	NCV6324BMTAAWTBG
NCV6323DMTAATBG	N/A	NCV6324BMTAAWTBG
NCV6323DMTAAWTBG	N/A	NCV6324BMTAAWTBG
NCV6324BMTAATBG	N/A	NCV6324BMTAAWTBG
NCV6324BMTAAWTBG	N/A	NCV6324BMTAAWTBG